XILINX®

PK423 (v1.0) September 30, 2010

100% Material Declaration Data Sheet FTG256 Package for Spartan-6 FPGAs

Average Weight: 0.7170g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					**0.01192**	**1.663**
	Silicon	7440-21-3	100.00		0.01192	
Die Attach Material					**0.002453**	**0.342**
	Silver	7440-22-4	77.50		0.001901	
	Bismaleimide Monomer	Trade Secret	15.00		0.000368	
	Acrylate Monomer	Trade Secret	7.50		0.000184	
Mold Compound					**0.384597**	**53.640**
	Solid Epoxy Resin	Trade Secret	5.00		0.019230	
	Phenol Resin	Trade Secret	5.00		0.019230	
	Fused Silica	60676-86-0	87.45		0.336330	
	Metal Hydroxide	Trade Secret	2.00		0.007692	
	Carbon Black	1333-86-4	0.55		0.002115	
Substrate					**0.184309**	**25.706**
	Copper	7440-50-8	14.12		0.026027	
	Nickel	7440-02-0	6.23		0.011479	
	Gold	7440-57-5	1.24		0.002284	
Core	Epoxy Resin	Trade Secret	24.33		0.044844	
	Inorganic Filler	21645-51-2	9.12		0.016809	
	Fiberglass	65997-17-3	24.32		0.044825	
	Copper	7440-50-8	3.04		0.005603	
Solder Mask	Talc	14807-96-6	0.88		0.001622	
	Morpholine Derivative	Trade Secret	0.53		0.000973	
	Barium Sulfate	7727-43-7	7.74		0.014272	
	Silica	7631-86-9	0.18		0.000324	
	Dipropylene Glycol Monomethyl Ether	34590-94-8	4.58		0.008434	
	Epoxy Resin	85954-11-6	3.70		0.006812	
Gold Wire					**0.009626**	**1.343**
	Gold	7440-57-5	99.05		0.009534	
	Palladium	7440-05-3	0.95		0.000091	
	Calcium	7440-70-2	0.00		0.000000	

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Solder Balls					**0.124093**	**17.307**
	Tin	7440-31-5	96.50		0.119750	
	Silver	7440-22-4	3.00		0.003723	
	Copper	7440-50-8	0.50		0.000620	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/30/10	1.0	Initial Xilinx release.

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